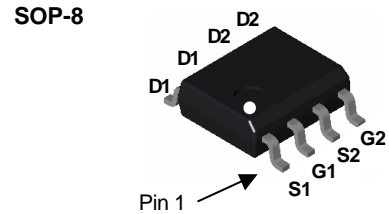
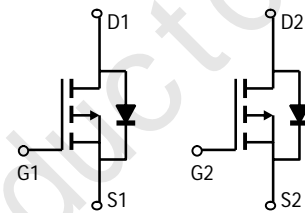


$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
-30V	0.059Ω@-10V	-5.3A
	0.089Ω@-4.5V	



#### Equivalent Circuit



#### MARKING



Y :year code W :week code

#### General FEATURE

- TrenchFET Power MOSFET
- Lead free product is acquired
- Surface mount package

#### APPLICATION

- Load Switch for Portable Devices
- DC/DC Converter

#### Maximum ratings ( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	±20	
Continuous Drain Current	$I_D$	-5.3	A
Pulsed Drain Current	$I_{DM}$	-20	
Maximum Power Dissipation	$P_D$	2.0	W
Thermal Resistance from Junction to Ambient( $t \leq 5s$ )	$R_{\theta JA}$	125	$^{\circ}\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature	$T_{stg}$	-55 ~+150	

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -24\text{ V}, V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
$I_{GSSF}$	Gate–Body Leakage, Forward	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$			-100	nA
$I_{GSSR}$	Gate–Body Leakage, Reverse	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$			100	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-1	-1.7	-3	V
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = -10\text{ V}, I_D = -5.3\text{ A}$		54	59	m $\Omega$
		$V_{GS} = -4.5\text{ V}, I_D = -4.2\text{ A}$		84	89	
$I_{D(on)}$	On–State Drain Current	$V_{GS} = -10\text{ V}, V_{DS} = -5.0\text{ V}$	-20			A
$g_{FS}$	Forward Transconductance	$V_{DS} = -5\text{ V}, I_D = -5\text{ A}$		10		S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -15\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$		528		pF
$C_{oss}$	Output Capacitance			132		pF
$C_{rss}$	Reverse Transfer Capacitance			70		pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = -15\text{ V}, I_D = -1\text{ A}, V_{GS} = -10\text{ V}, R_{GEN} = 6\ \Omega$		7		ns
$t_r$	Turn–On Rise Time			13		ns
$t_{d(off)}$	Turn–Off Delay Time			14		ns
$t_f$	Turn–Off Fall Time			9		ns
$Q_g$	Total Gate Charge	$V_{DS} = -15\text{ V}, I_D = -5\text{ A}, V_{GS} = -5\text{ V}$		6.0	9	nC
$Q_{gs}$	Gate–Source Charge			2.2		nC
$Q_{gd}$	Gate–Drain Charge			2.0		nC
<b>Drain–Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain–Source Diode Forward Current				-1.3	A
$V_{SD}$	Drain–Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -2.6\text{ A}$		-0.8	-1.2	V

**Notes:**

- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.

### Typical Characteristics

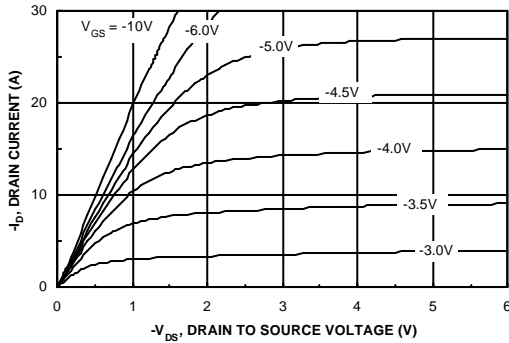


Figure 1. On-Region Characteristics.

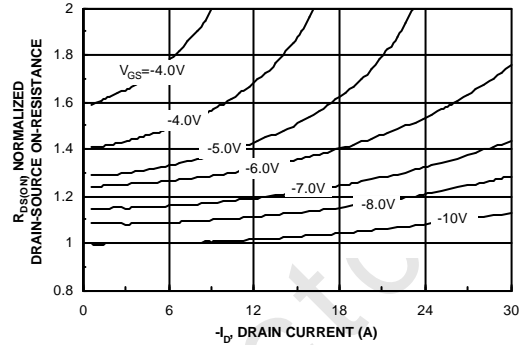


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

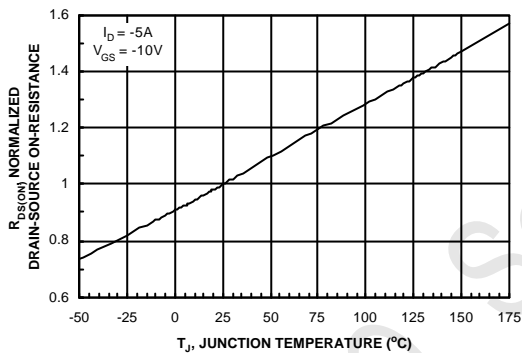


Figure 3. On-Resistance Variation with Temperature.

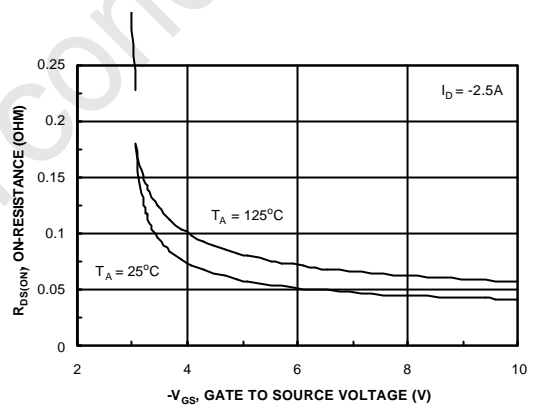


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

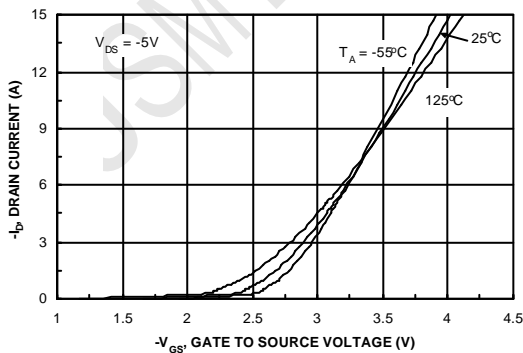


Figure 5. Transfer Characteristics.

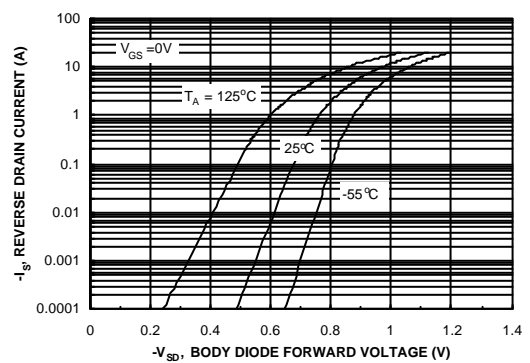


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

### Typical Characteristics

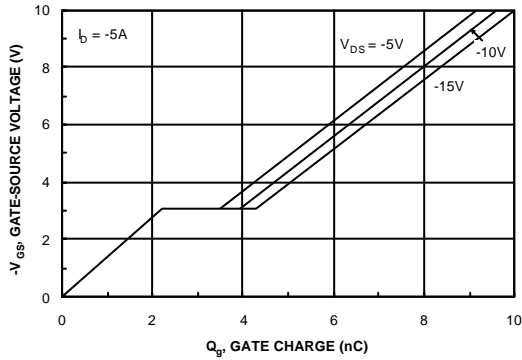


Figure 7. Gate Charge Characteristics.

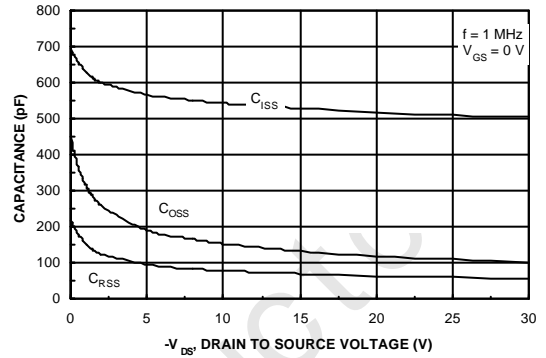


Figure 8. Capacitance Characteristics.

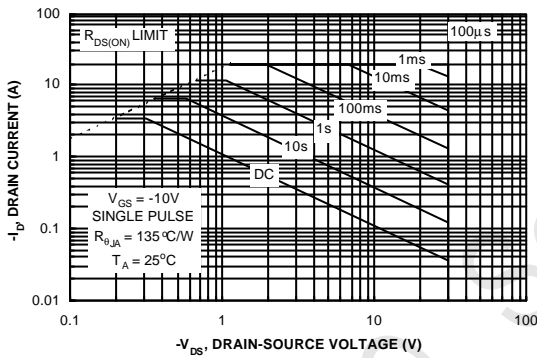


Figure 9. Maximum Safe Operating Area.

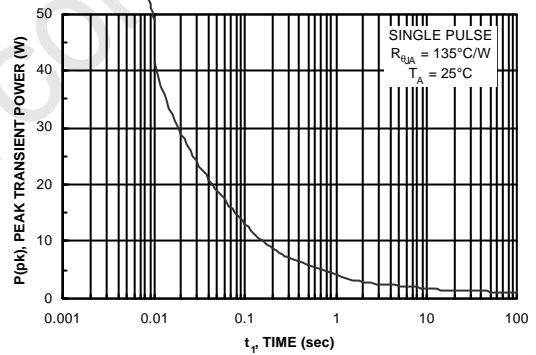


Figure 10. Single Pulse Maximum Power Dissipation.

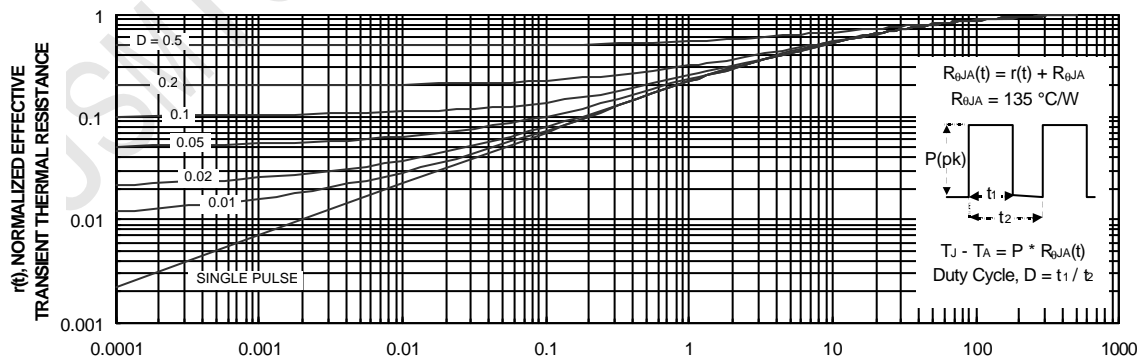
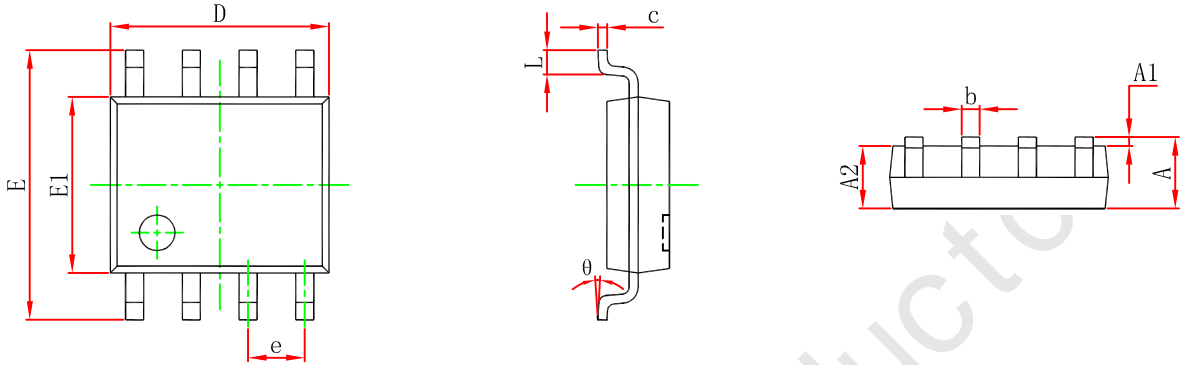


Figure 11. Transient Thermal Response Curve.

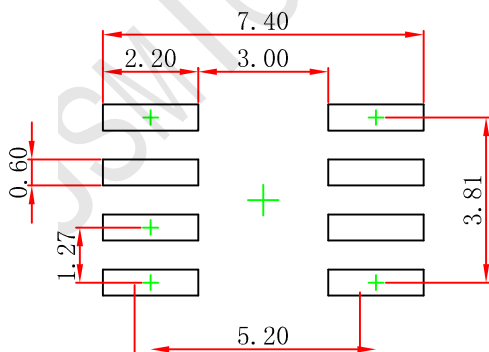
Thermal characterization performed using the conditions described in Note 1c.  
 Transient thermal response will change depending on the circuit board design.

### SOP8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

### SOP8 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.